

FIG. 1A

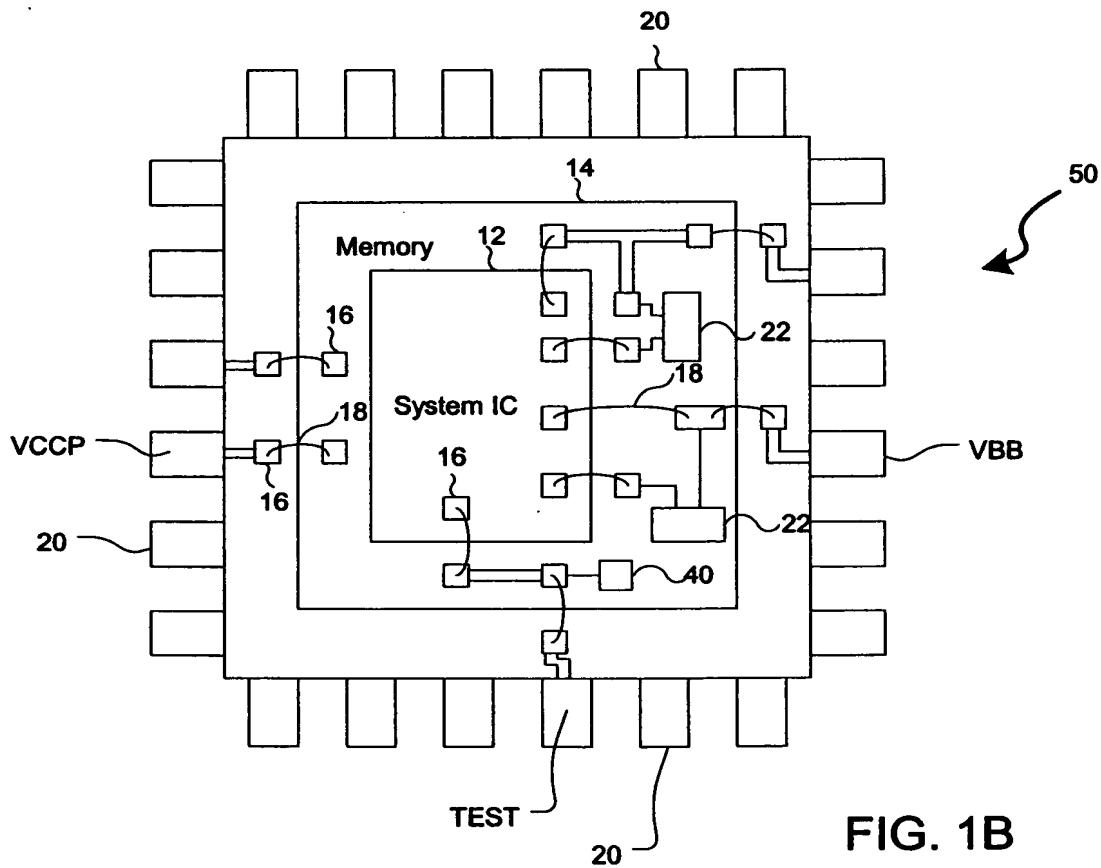


FIG. 1B

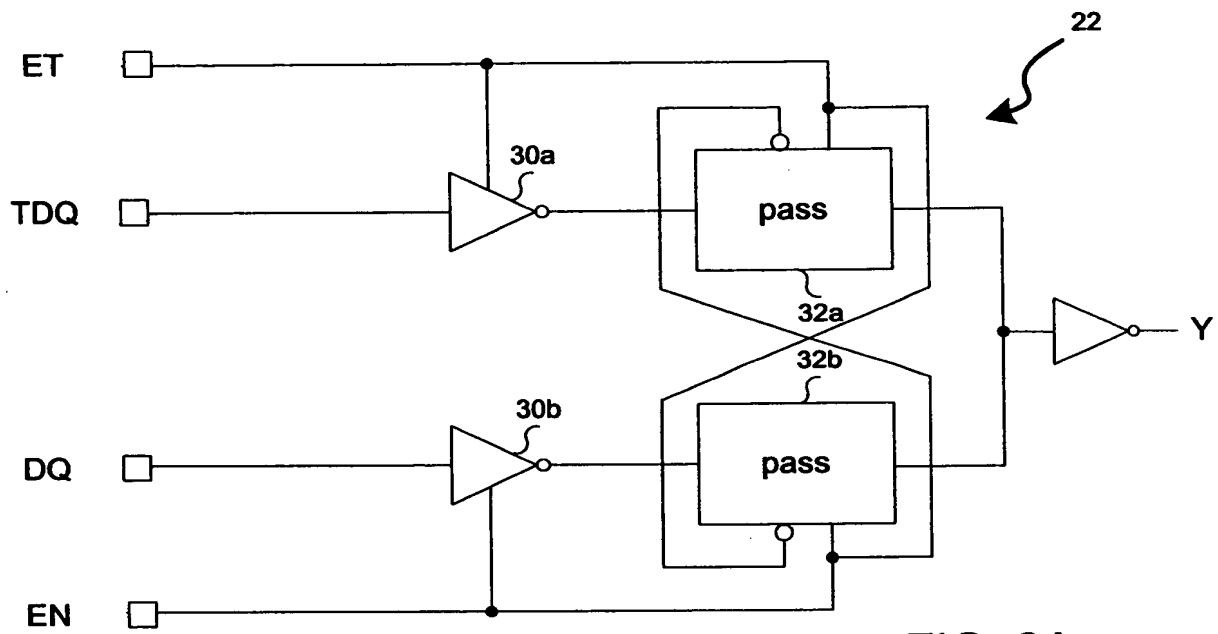


FIG. 2A

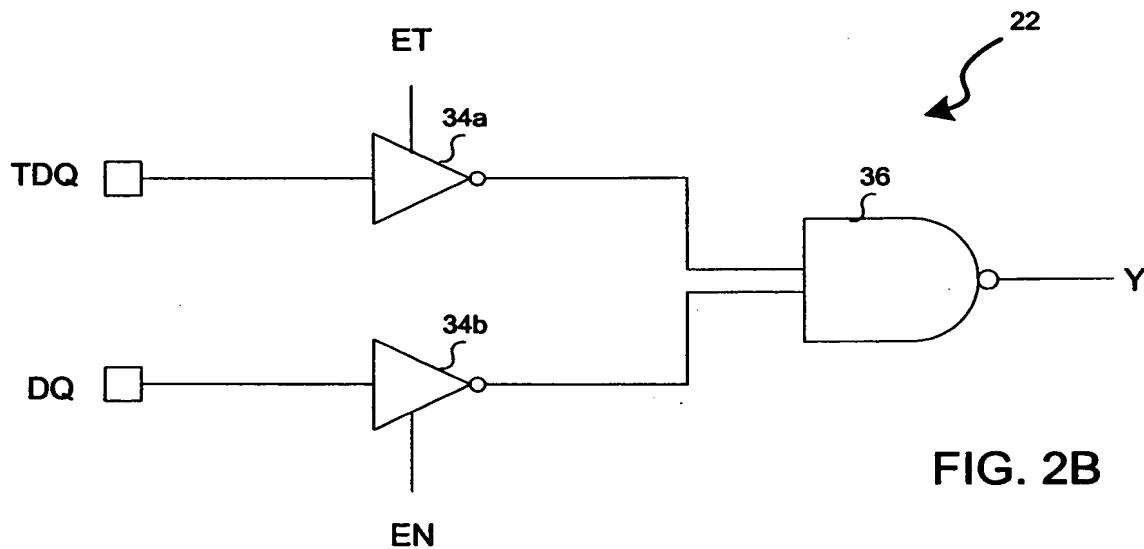


FIG. 2B

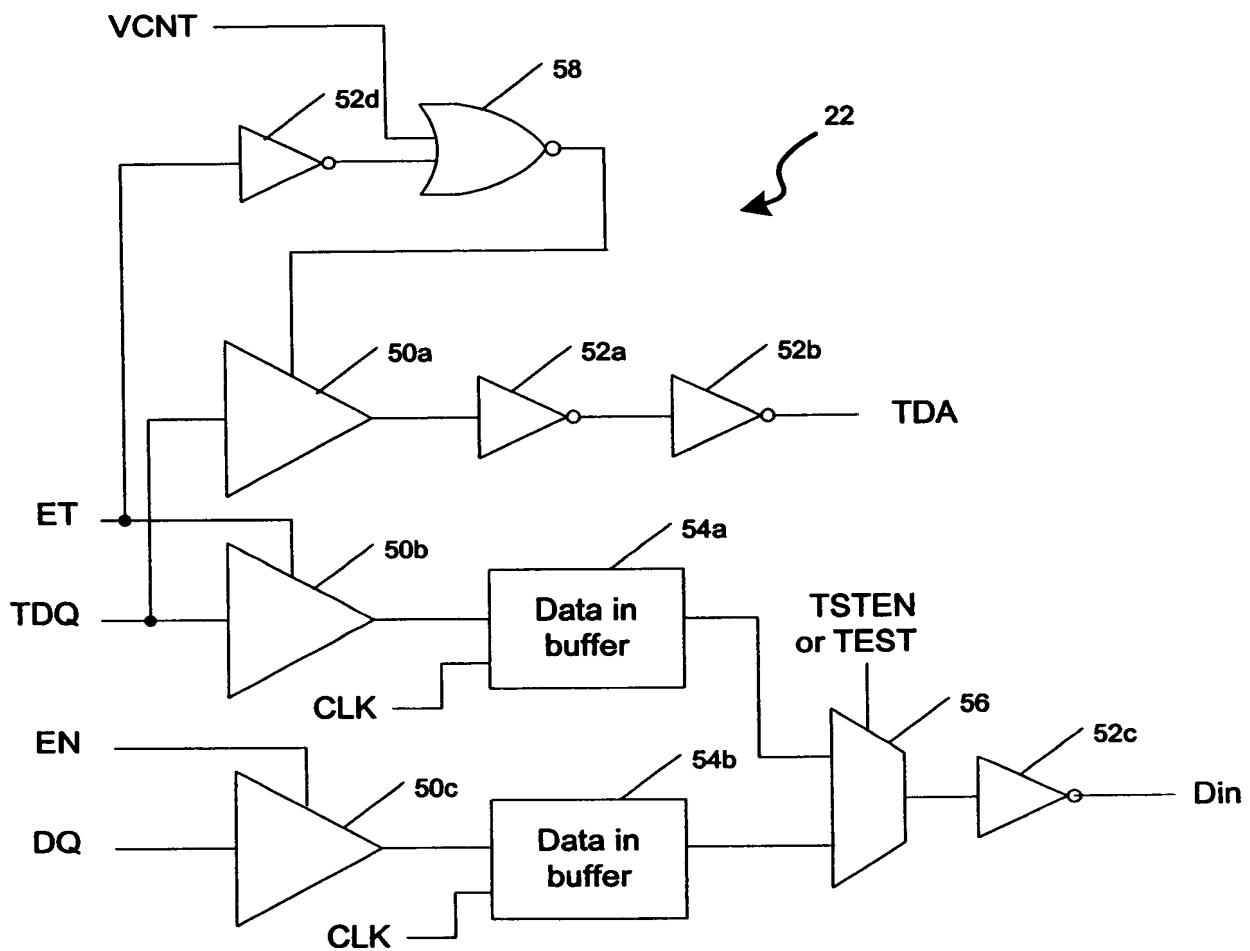


FIG. 2C

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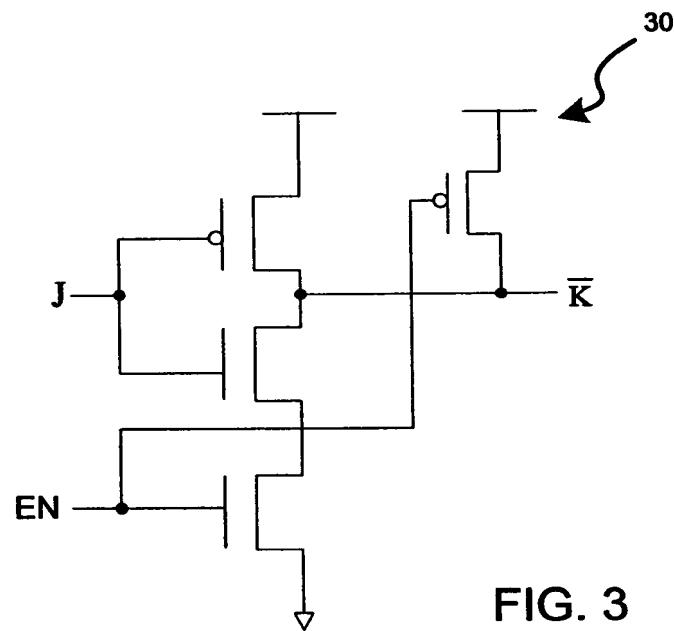


FIG. 3

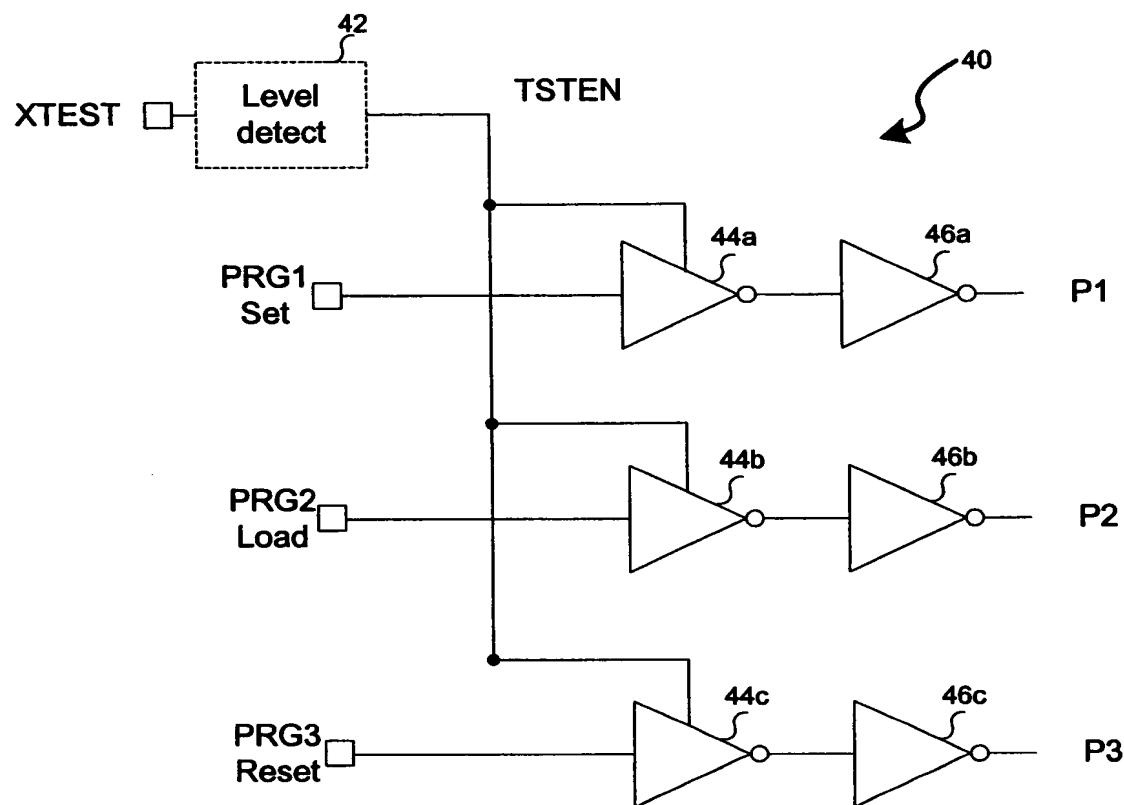


FIG. 4

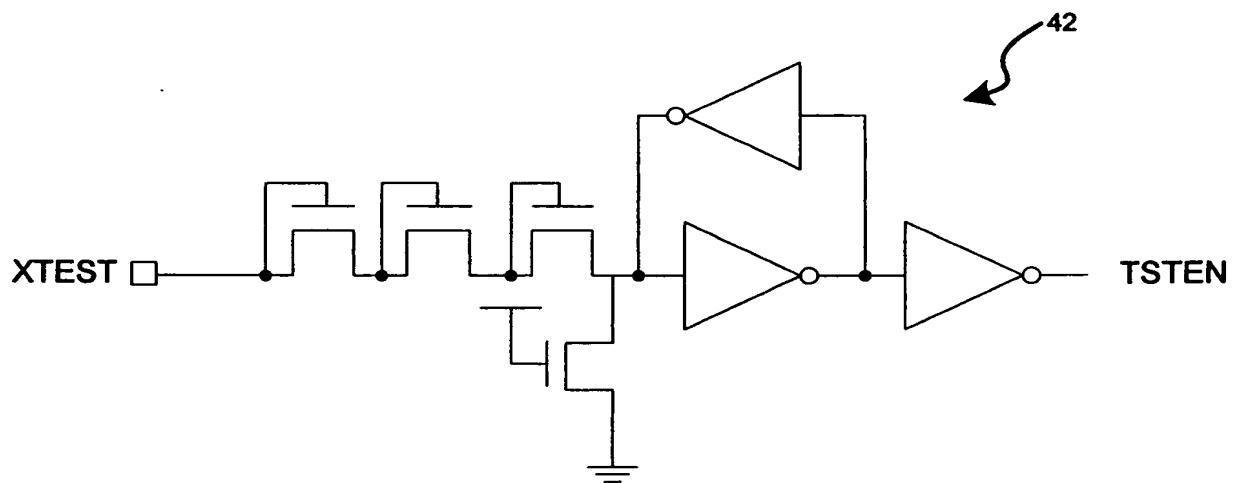


FIG. 5

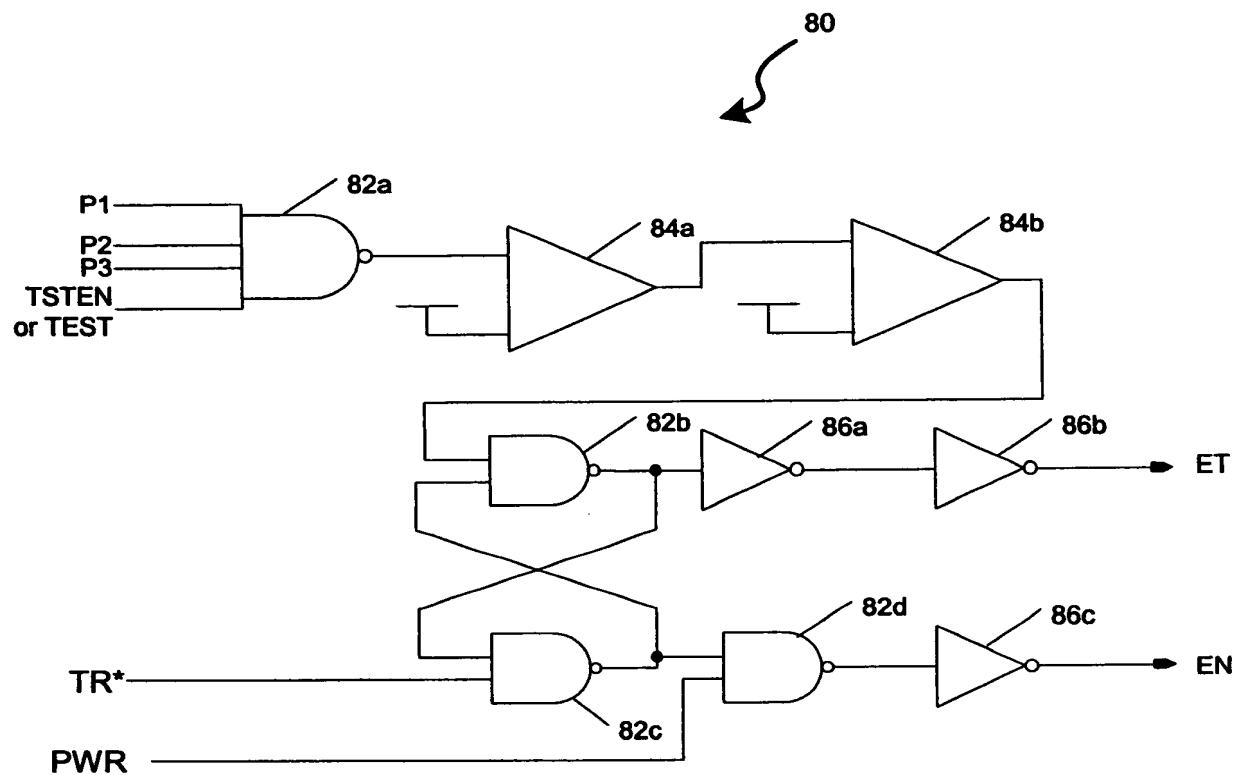


FIG. 6

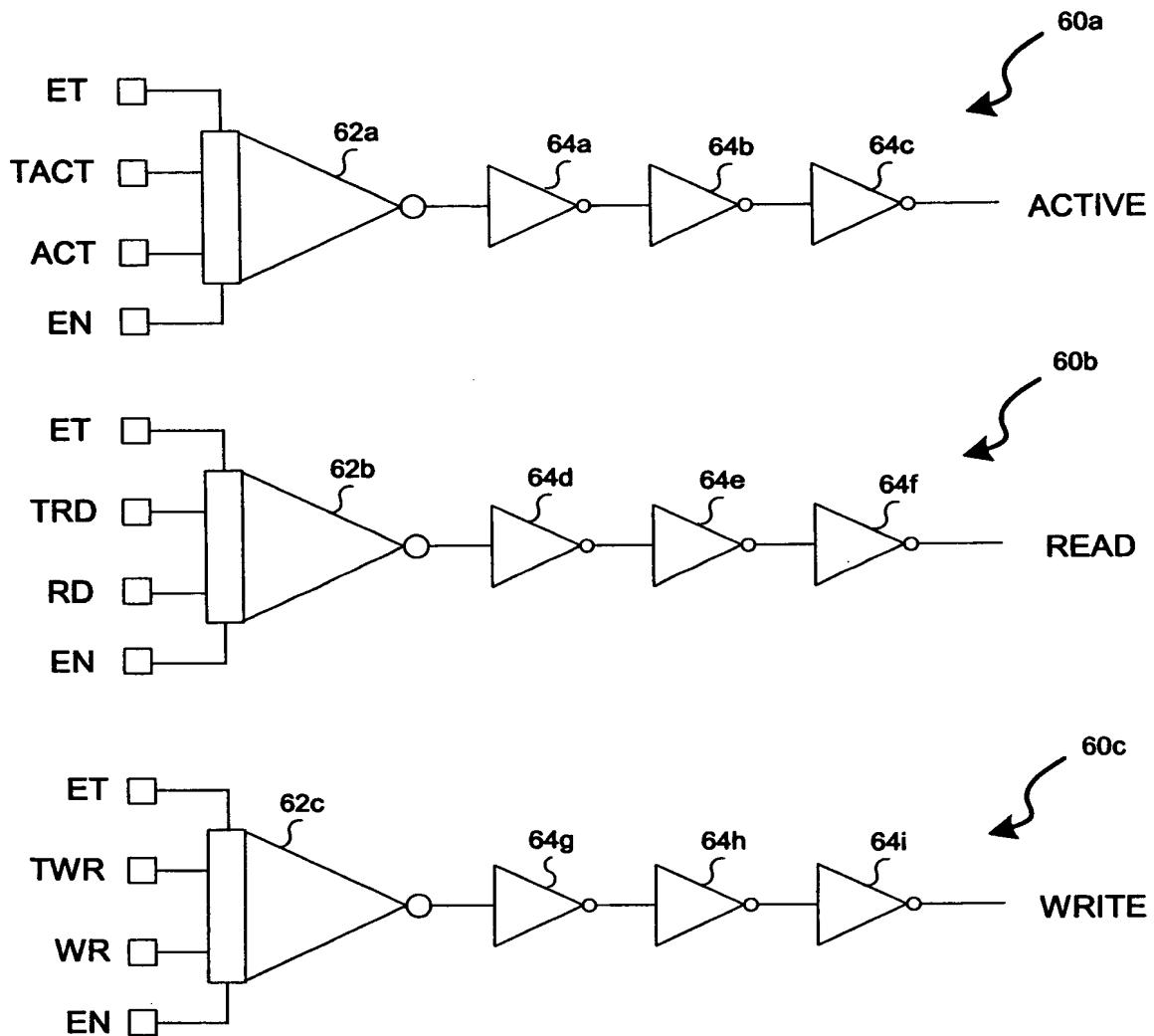


FIG. 7

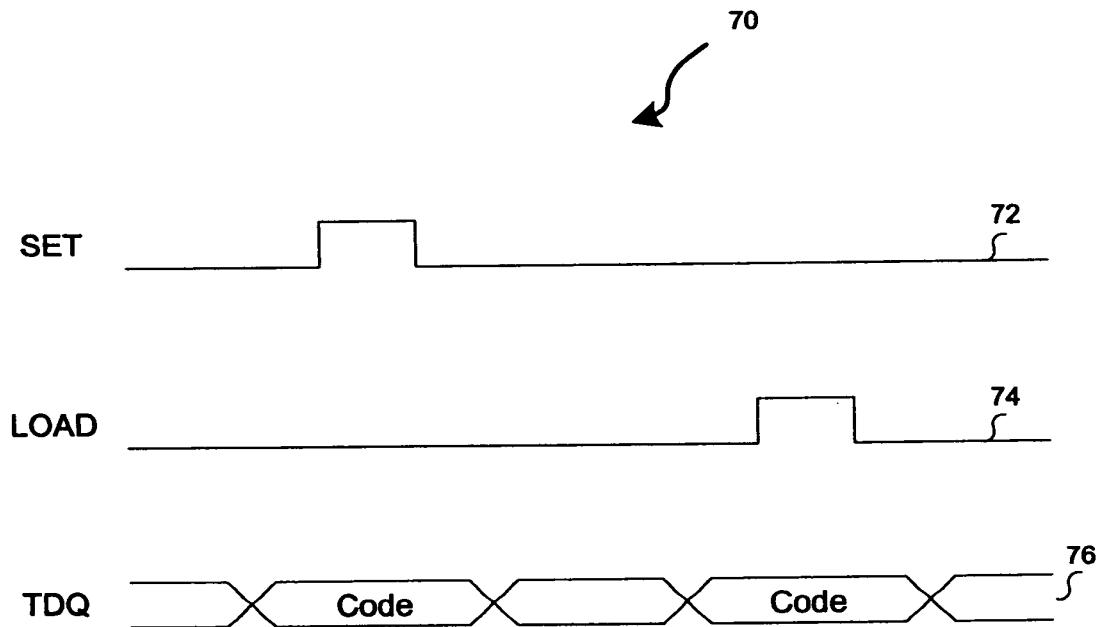


FIG. 8

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100

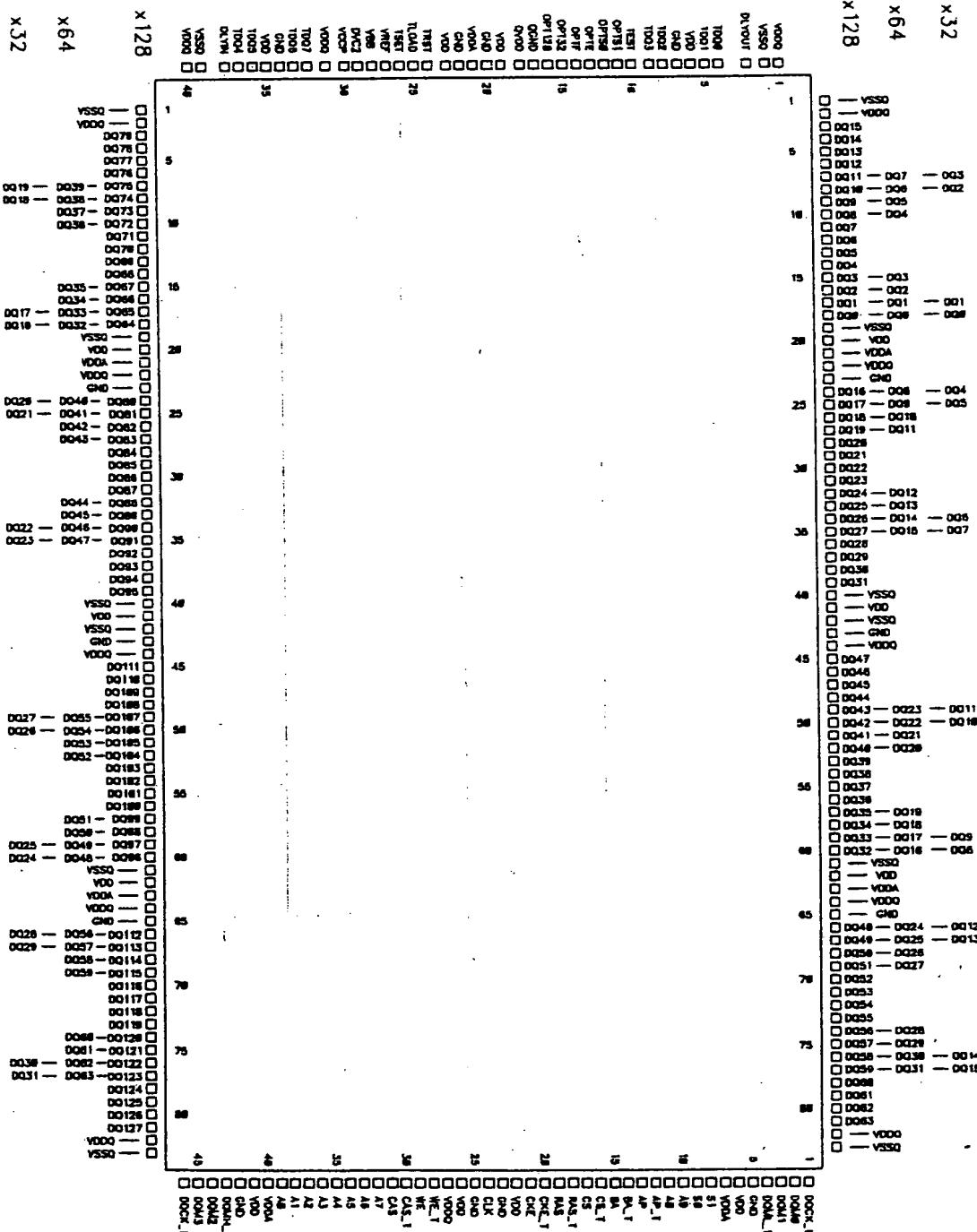


FIG. 9A

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Device"**
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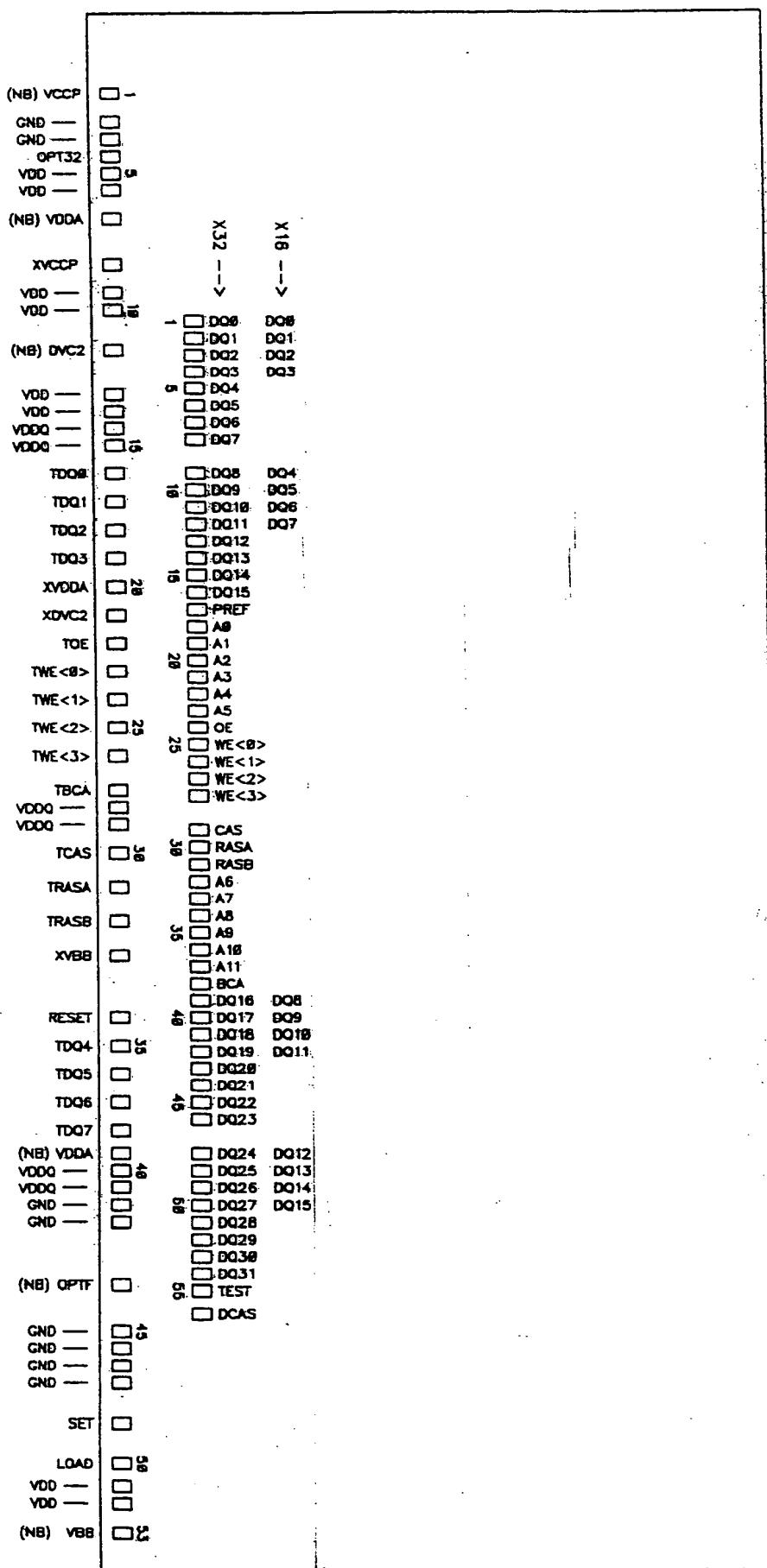


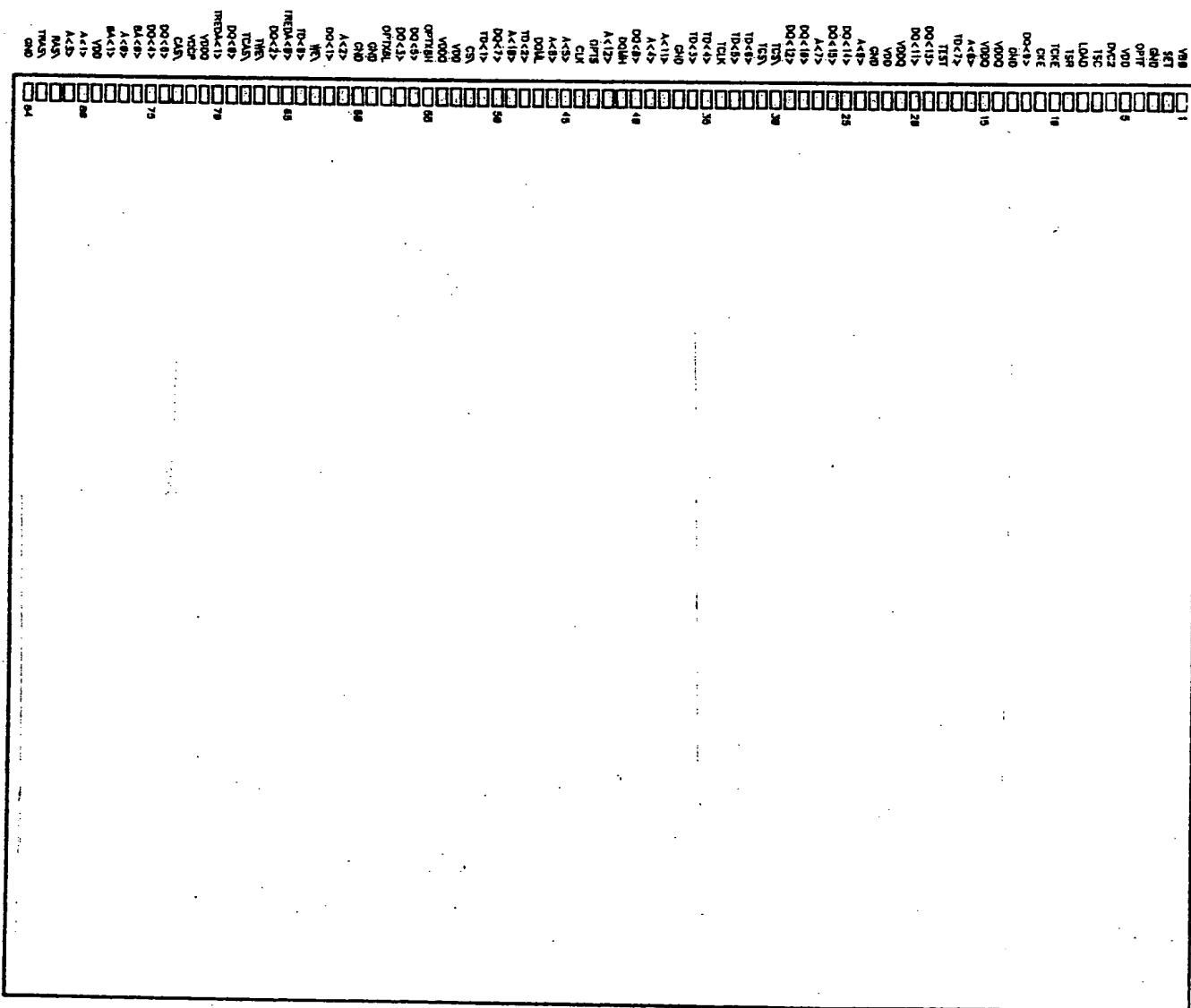
FIG. 9B

45 200

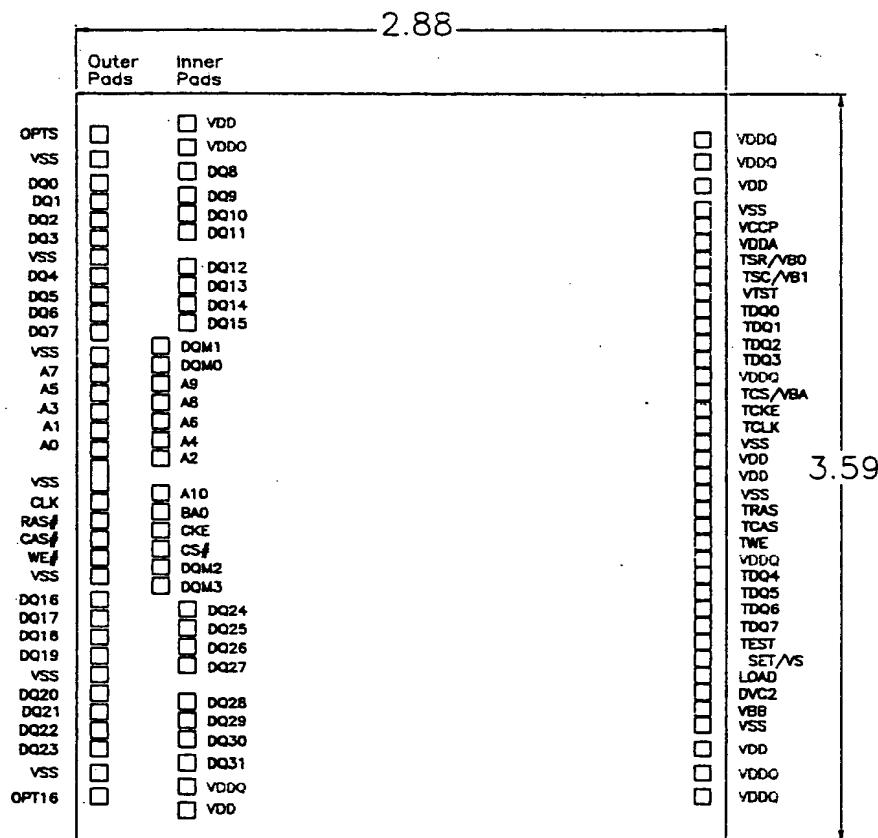
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2
300



3.59

400

FIG. 9D

"Bonding Pads For Testing Of A Semiconductor Device"
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Outer Pads
Inner Pads

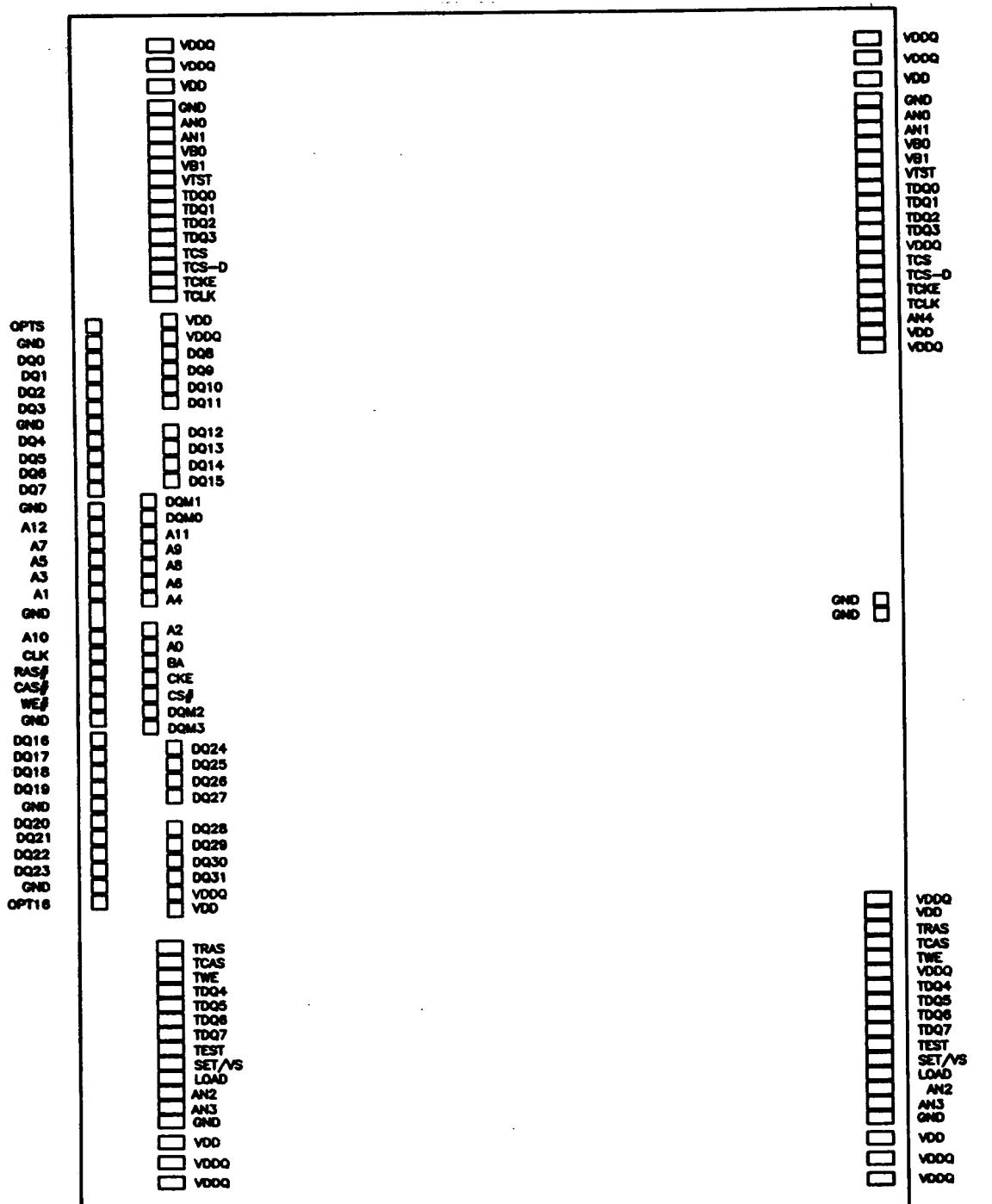


FIG. 9E